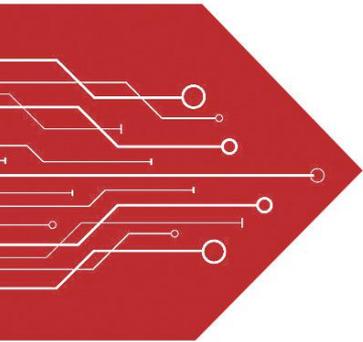


# MSKSEMI

SEMICONDUCTOR



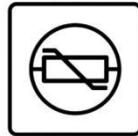
ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

**VOLTAGE RANGE**

50 to 1000 Volts

**CURRENT**

10.0 Ampere



**SMC**

**FEATURES**

- \* Ideal for surface mount applications
- \* Easy pick and place
- \* Built-in strain relief
- \* Low forward voltage drop

**MECHANICAL DATA**

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Metallurgically bonded construction
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any
- \* Weight: 0.21 grams

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

P/N(MARK)	S10A	S10B	S10D	S10G	S10J	S10K	S10M	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Ta=75°C	10.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	175							A
Maximum Instantaneous Forward Voltage at 10.0A	1.10							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=125°C	250							μA
Typical Junction Capacitance (Note1)	70							pF
Typical Thermal Resistance RθJL (Note 2)	13							°C/W
Operating and Storage Temperature Range Tj, Tstg	-65 — +150							°C

**NOTES:**

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (S10A THRU S10M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

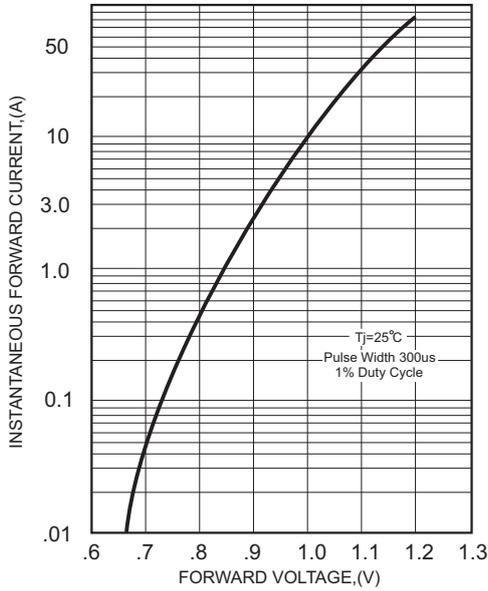


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

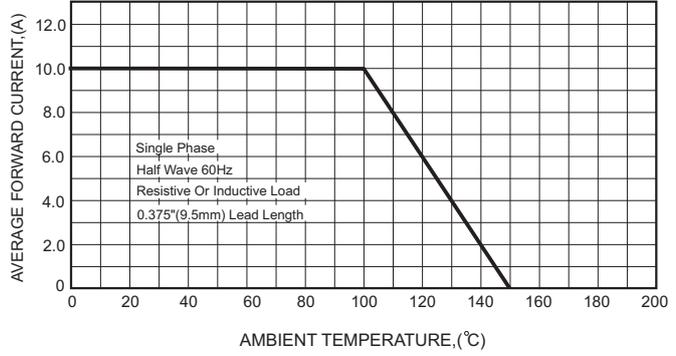


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

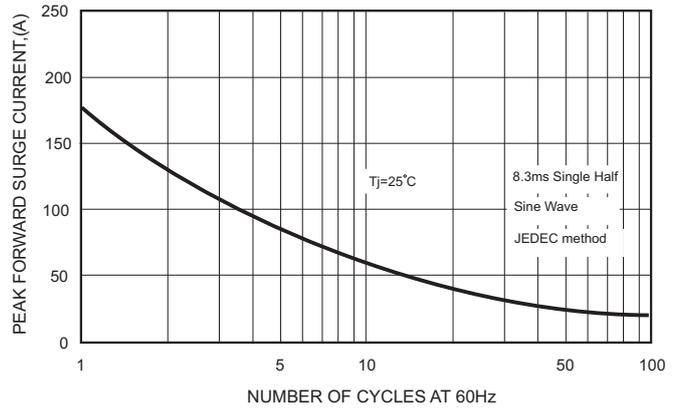


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

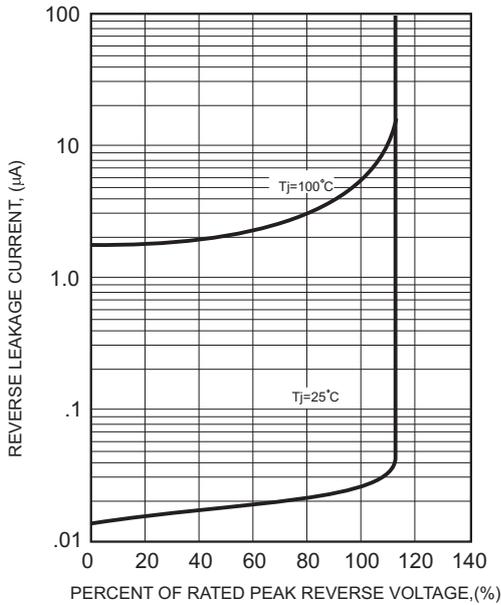
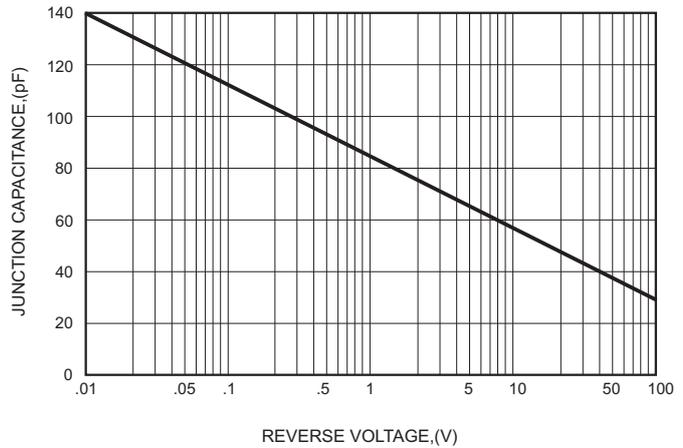
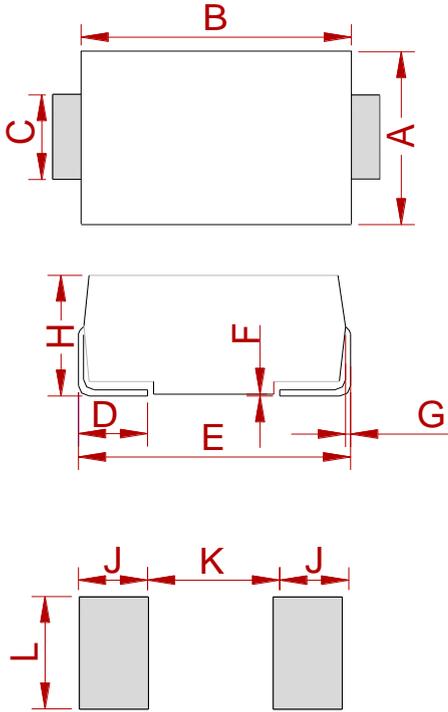


FIG.5-TYPICAL JUNCTION CAPACITANCE



**PACKAGE MECHANICAL DATA**



SMC

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

**REEL SPECIFICATION**

P/N	PKG	QTY
S10A THRU S10M	SMC	3000

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